



PATENT  
81751.0017

In re application of:

Kazunobu KUWAZAWA

Serial No: 09/943,094

Filed: August 29, 2001

For: SEMICONDUCTOR DEVICE AND  
METHOD OF MANUFACTURING THE  
SAME

Art Unit: 2826

Examiner: Ahmed N. Sefer

#10/B  
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**AMENDMENT**

Box Non Fee Amendment

Commissioner for Patents

Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated September 12, 2002, please amend the above-referenced application as follows:

**IN THE CLAIMS:**

Please replace claims 1, 5 and 7 as follows:

1. (Amended) A semiconductor device comprising:
- a semiconductor substrate having a first conductive layer provided thereon;
  - an insulation layer provided above the semiconductor substrate;
  - a semiconductor layer provided above the insulation layer, wherein the semiconductor layer includes an element isolation region which has a connection hole;
  - a second conductive layer provided above the semiconductor layer or in the semiconductor layer, and electrically connected to the first conductive layer; and
  - a contact layer provided in the connection hole, the contact layer electrically connecting the first conductive layer and the second conductive layer.

5. (Amended) The semiconductor device as defined by claim 1,

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